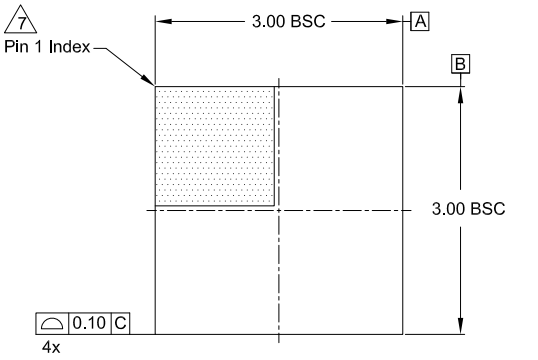
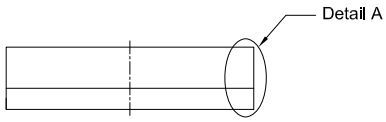
Package Outline Drawing

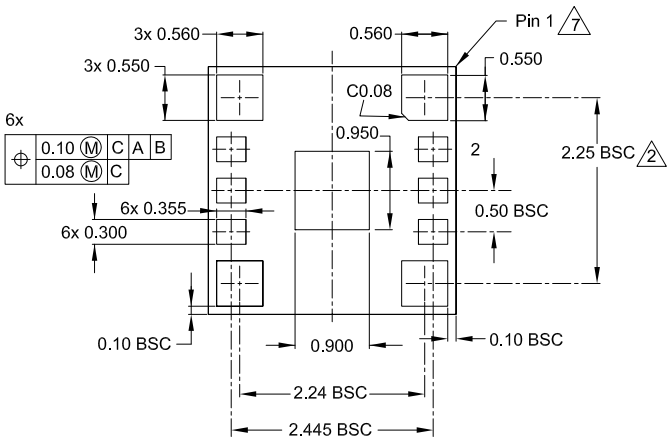
Y10.3x3
10 Lead Dual Flat Embedded Laminate Package
Rev 1, 9/20



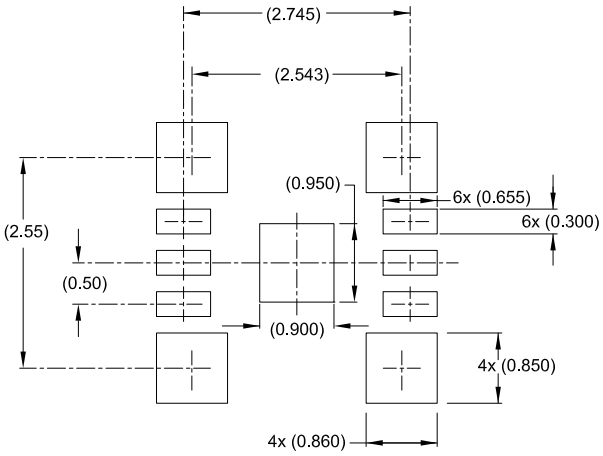
Top View



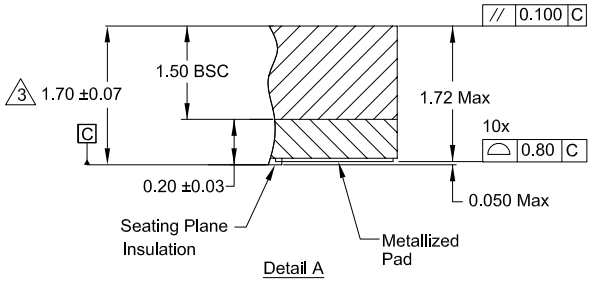
Side View



Bottom View



Recommended PCB Land Pattern



Detail A

Notes :

1. All dimensions are in mm.
   Dimensions in ( ) for reference only.
2. Represents the basic terminal pitch.
   Specifies the true geometric position of the terminal axis.
3. Dimension includes package warpage.
4. Exposed metallized pads are Cu pads with surface finish protection.
5. Package dimensions refer to JEDEC MO-208 rev.c.
6. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
   Unless otherwise specified, tolerance: Decimal ±0.05
7. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier can be either a mold or mark feature.